

ABSTRACT OF THE DISCLOSURE

A sensor device includes a circuit chip, an adhesion film, and a sensor chip mounted on the circuit chip through the adhesion film. The sensor chip includes a substrate having foreside and backside surfaces, a concavity disposed on the backside surface of the substrate, and a membrane disposed on the foreside surface of the substrate so that the membrane covers the concavity. The adhesion film is disposed between the sensor chip and the circuit chip so as to form a passage for connecting between the concavity and an outside of the concavity.